Antenna/Modules in Package for mmWave for 5G

Dr. Rajesh Mandamparambil & Dr. Rob Maaskant

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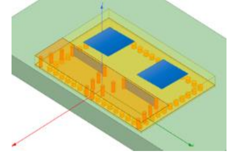
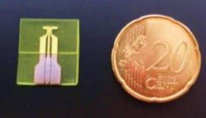
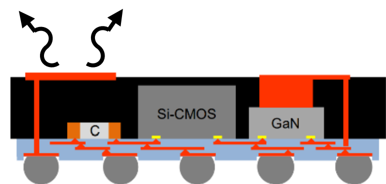
Dr. Stefania Monni

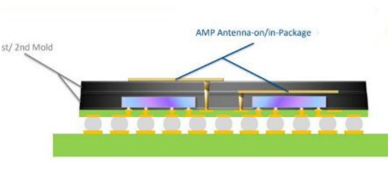
- Design considerations on printed antennas, transmission lines, and interconnects
- Packaging technologies
- Antenna-in-Package (AiP) design example
- Additive Manufacturing for Packaging: an Overview, 3D-printing

Dr.-Ing. Tanja Braun



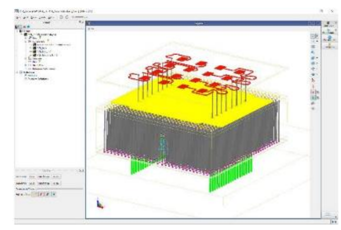
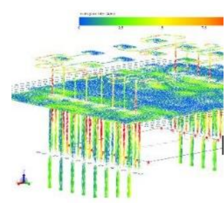
- Fan Out Wafer Level Packaging (FOWLP)
- Antenna-in-Package using FOWLP
- III/V semiconductor integration
- Package examples, prototyping oppurtinities and outlook

Ing. Ruud de Wit



- RF packaging material Innovations
- Package level EMI shielding
- High conductivity die attach for System in Package
- Liquid wafer level encapsulation
- Package Level Capillary Underfills – Thermal Interface Material

Dr. Alexander Kravets

- Wafer-level package reference flow
- Multi-Technology Assembly: Smart Mount
- Electromagnetic Analysis: RFPro
- Correlations with Measurements

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